

# 15A, 60V Schottky Barrier Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Low power loss, high efficiency
- Ideal for automated placement
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

#### **APPLICATIONS**

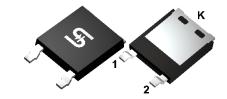
- Low voltage, high frequency, inverter
- DC/DC converter
- Freewheeling diodes
- · Reverse battery protection
- Car lighting

### **MECHANICAL DATA**

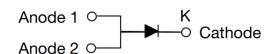
- Case: ThinDPAK
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.196g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
l <sub>F</sub>	15	Α	
$V_{RRM}$	60	V	
I <sub>FSM</sub>	250	Α	
T <sub>J MAX</sub>	150	°C	
Package	ThinDPAK		
Configuration	Single die		





**ThinDPAK** 



PARAMETER		SYMBOL	MBRAD1560H	UNIT
Marking code on the device			1560	
Repetitive peak reverse voltage		$V_{RRM}$	60	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	42	V
Forward current		lF	15	А
Surge peak forward current single half sine-wave superimposed on rated load	t = 8.3ms		250	А
	t = 1.0ms	IFSM	450	А
Junction temperature	•	TJ	-55 to +150	°C
Storage temperature		T <sub>STG</sub>	-55 to +150	°C



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance <sup>(1)</sup>	R <sub>OJL</sub>	2.2	°C/W
Junction-to-ambient thermal resistance <sup>(2)</sup>	Reja	12	°C/W
Junction-to-case thermal resistance <sup>(2)</sup>	Rejc	2.6	°C/W

## Notes:

- 1. With ideal heat sink
- 2. Units mounted on 2" x 3" x 0.25" Al-plate

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 7.5A, T <sub>J</sub> = 25°C	VF	0.58	-	V
	$I_F = 15A, T_J = 25^{\circ}C$		0.70	0.75	V
	I <sub>F</sub> = 7.5A, T <sub>J</sub> = 125°C		0.50	-	V
	I <sub>F</sub> = 15A, T <sub>J</sub> = 125°C		0.61	0.66	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	· I <sub>R</sub>	-	100	μA
	T <sub>J</sub> = 125°C		-	20	mA
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	576	-	pF

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

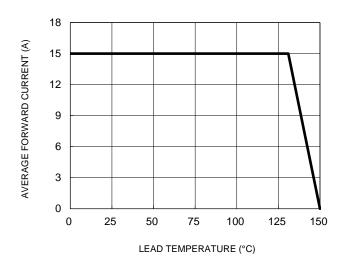
ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
MBRAD1560H	ThinDPAK	4,500 / Tape & Reel	



### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve



**Fig.2 Typical Junction Capacitance** 

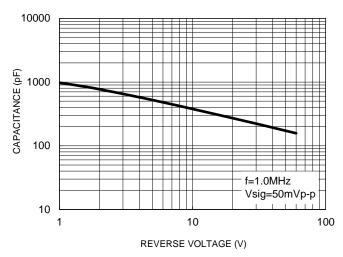
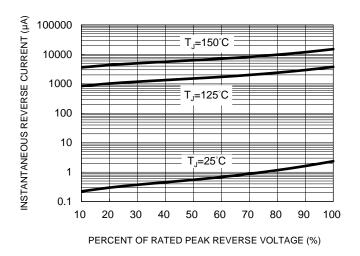


Fig.3 Typical Reverse Characteristics

Fig.4 Typical Forward Characteristics



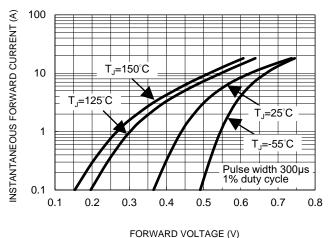
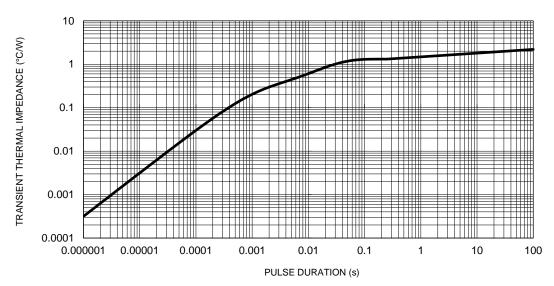


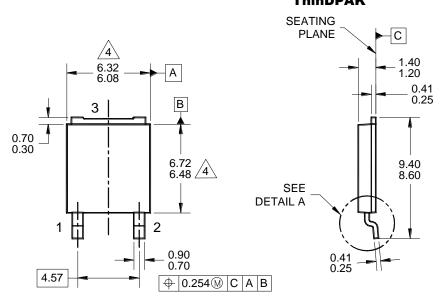
Fig.5 Typical Transient Thermal Impedance

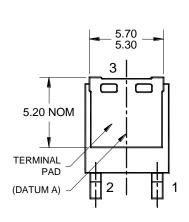


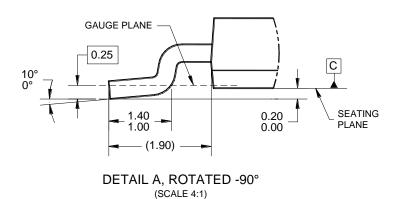


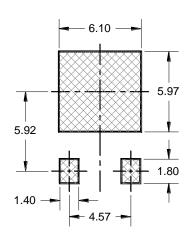
### **PACKAGE OUTLINE DIMENSIONS**

# ThinDPAK

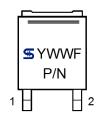








SUGGESTED PAD LAYOUT



### MARKING DIAGRAM

YWW = DATE CODE F = FACTORY CODE P/N = MARKING CODE

#### NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-252, VARIATION AE, ISSUE F.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION, OR GATE BURRS.
  - 5. DWG NO. REF: HQ2SD07-TDPAK-065 REV A.



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